

Single N-Channel MOSFET

DESCRIPTION

SMC2208E is the N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced trench technology devices are well suited for high efficiency fast switching applications, low in-line power loss needed in small outline surface mount package.

PART NUMBER INFORMATION

SMC 2208 E SD - TR G
 a b c d e f

- a : Company name.
- b : Product Serial number.
- c : ESD
- d : Package code SD: SOT-723
- e : Handling code TR: Tape&Reel
- f : Green produce code G: *RoHS Compliant*

FEATURES

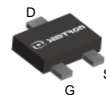
$V_{DS} = 20V, I_D = 0.8A$

- $R_{DS(ON)} = 200m\Omega(Typ.) @ V_{GS} = 4.5V$
- $R_{DS(ON)} = 300m\Omega(Typ.) @ V_{GS} = 2.5V$
- $R_{DS(ON)} = 500m\Omega(Typ.) @ V_{GS} = 1.8V$
- $R_{DS(ON)} = 800m\Omega(Typ.) @ V_{GS} = 1.5V$

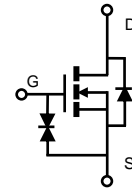
- ◆ Fast switch
- ◆ Low gate drive applications
- ◆ Low Input Capacitance

APPLICATIONS

- ◆ Hand-Held Instruments
- ◆ Load Switch
- ◆ Battery Protection



SOT-723



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless otherwise noted)

Symbol	Parameter	Rating	Units	
V_{DSS}	Drain-Source Voltage	20	V	
V_{GSS}	Gate-Source Voltage	± 8	V	
I_D	Continuous Drain Current	$T_A = 25^\circ C$	0.8	A
		$T_A = 70^\circ C$	0.7	A
I_{DM}	Pulsed Drain Current ^A	3.2	A	
P_D	Power Dissipation ^B	$T_A = 25^\circ C$	0.3	W
		$T_A = 70^\circ C$	0.2	W
T_J	Operation Junction Temperature	-55/150	$^\circ C$	
T_{STG}	Storage Temperature Range	-55/150	$^\circ C$	

THERMAL RESISTANCE

Symbol	Parameter	Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient ^C	$t \leq 10s$	-	$^\circ C/W$
	Thermal Resistance Junction to Ambient ^C	Steady-State	280	

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ Unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Parameters						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	20			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.3	0.5	0.85	V
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±8V			±20	μA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V T _J =25°C			1	μA
		V _{DS} =16V, V _{GS} =0V T _J =75°C			10	
R _{DS(ON)}	Drain-source On-Resistance ^D	V _{GS} =4.5V, I _D =0.5A V _{GS} =2.5V, I _D =0.4A V _{GS} =1.8V, I _D =0.2A V _{GS} =1.5V, I _D =0.1A		200 300 500 800	300 450 700 1200	mΩ
Source-Drain Diode						
V _{SD}	Diode Forward Voltage ^B	I _S =1A, V _{GS} =0V			1.0	V
I _S	Continuous Source Current				0.8	A
Dynamic and Switching Parameters						
Q _g	Total Gate Charge	V _{DS} =10V, V _{GS} =4.5V I _D =0.8A		1	1.3	nC
Q _{gs}	Gate-Source Charge			0.26	0.33	
Q _{gd}	Gate-Drain Charge			0.2	0.27	
C _{iss}	Input Capacitance	V _{DS} =10V, V _{GS} =0V f =1MHz		39	46	pF
C _{oss}	Output Capacitance			14	18	
C _{rss}	Reverse Transfer Capacitance			6	7.8	
t _{d(on)}	Turn-On Time ^E	V _{DD} =10V, V _{GEN} =4.5V, R _G =10Ω, I _D =0.5A		5		nS
t _r				3.5		
t _{d(off)}	Turn-Off Time ^E			14		
t _f				6		

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

A. The value of R_{θJA} is measured with the device in a still air environment with maximum junction temperature T_{J(MAX)} = 150°C (initial temperature T_A = 25°C)..

B. The T_{J(MAX)} = 150°C, using junction-to-ambient thermal resistance.

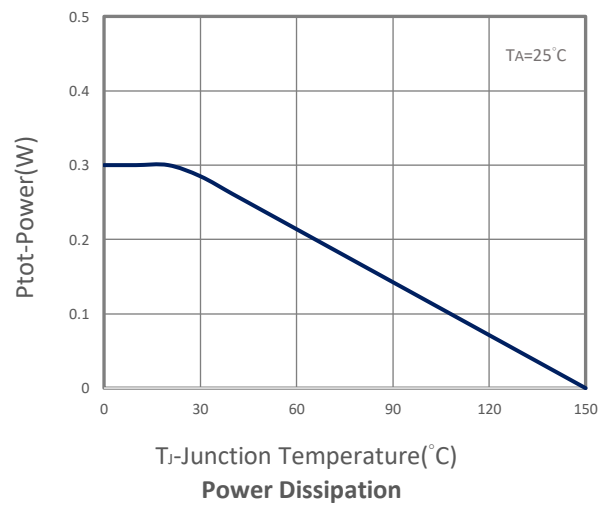
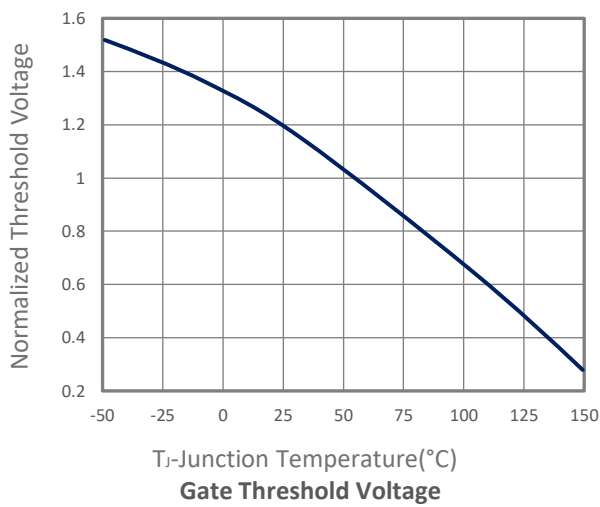
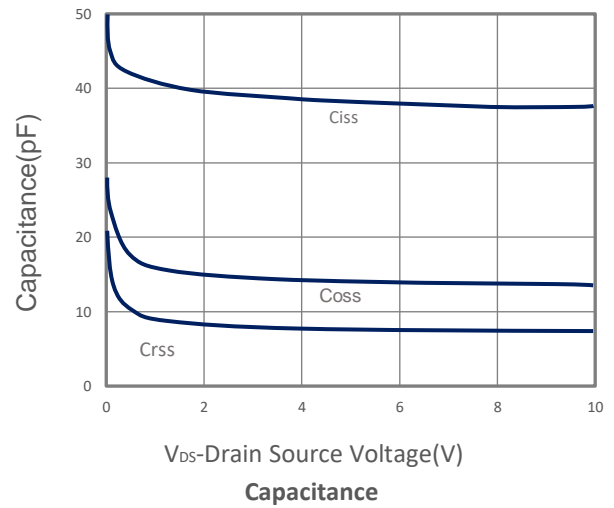
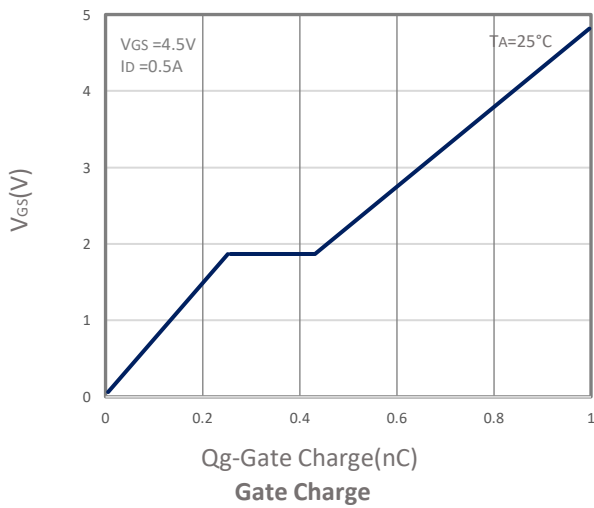
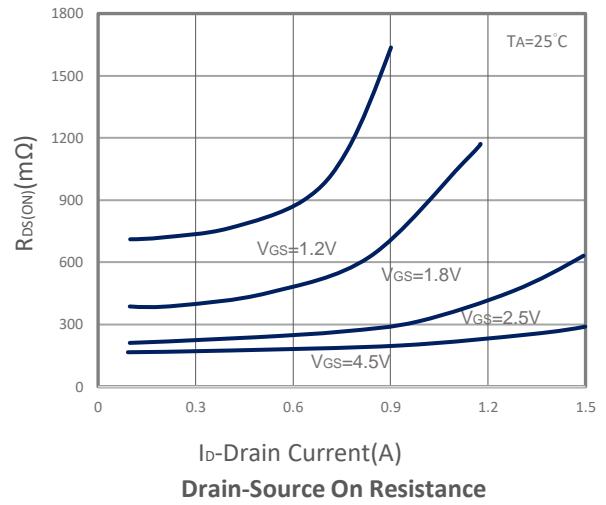
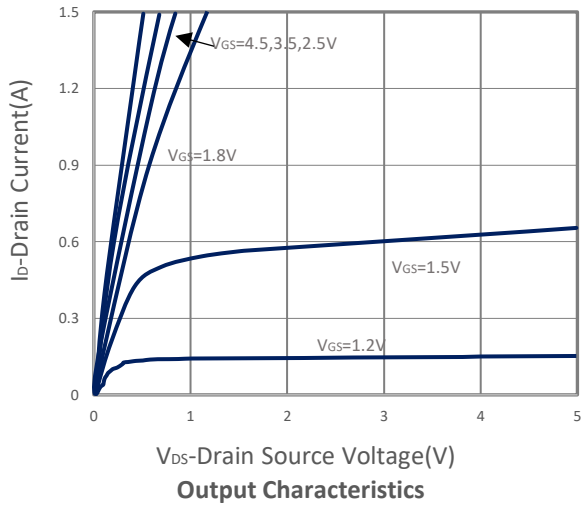
C. Surface-mounted on FR-4 board using 1 sq-in pad, 2 oz Cu, in a still air environment with T_A = 25°C.

D. The data tested by pulsed , pulse width ≤ 300μs , duty cycle ≤ 2%

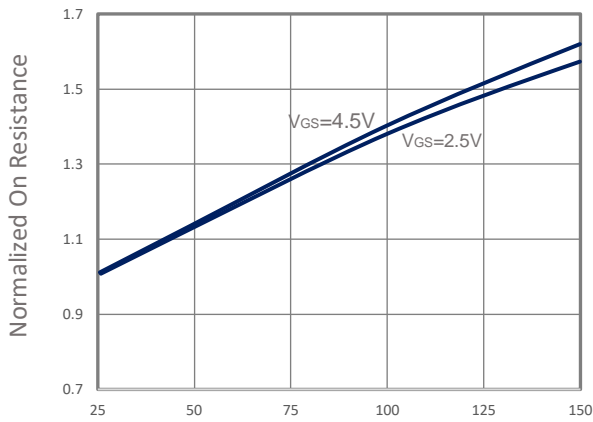
E. Pulsed width limited by maximum junction temperature.

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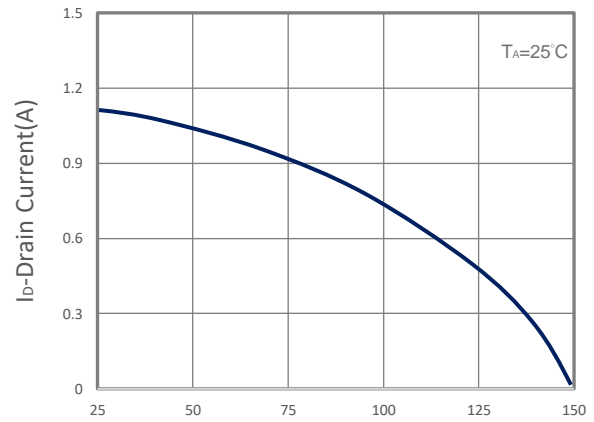
TYPICAL CHARACTERISTICS



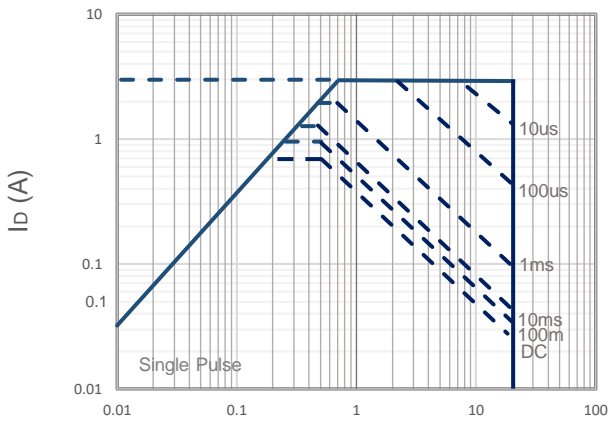
TYPICAL CHARACTERISTICS



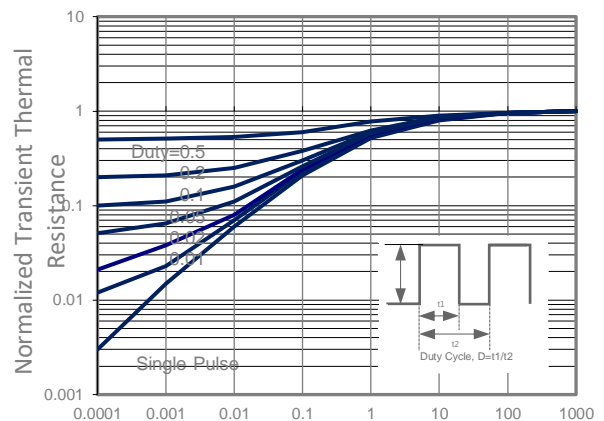
$R_{DS(on)}$ vs Junction Temperature



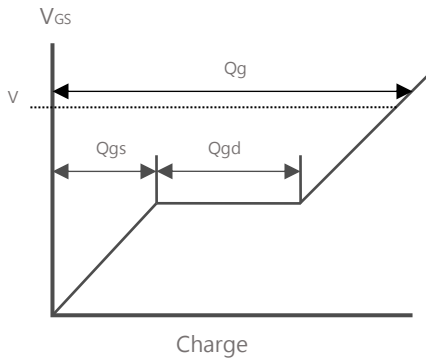
Drain Current vs T_j



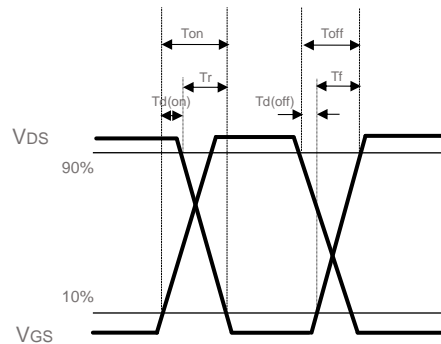
Maximum Safe Operation Area



Thermal Transient Impedance

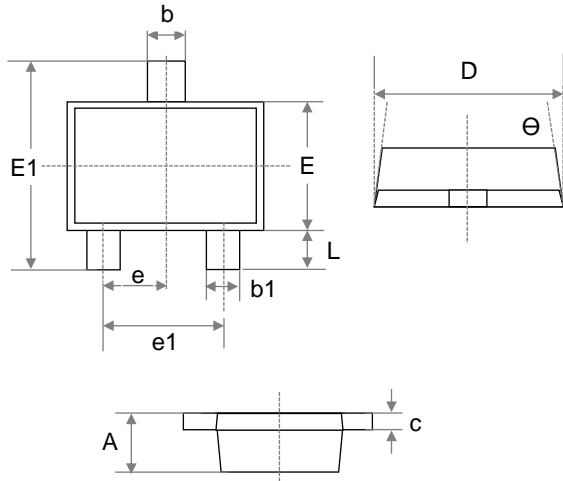


Gate Charge Waveform

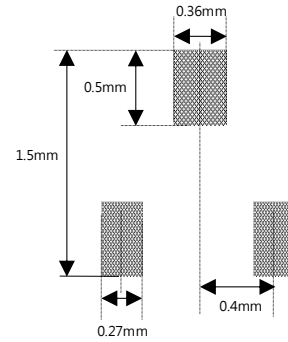


Switching Time Waveform

POD-050C_SOT-723 PACKAGE DIMENSIONS



Recommended Land Pattern



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.370	0.390	0.015	0.015
b	0.220	0.270	0.009	0.011
b1	0.170	0.220	0.007	0.009
c	0.009	0.011	0.003	0.004
D	1.150	1.250	0.045	0.049
E	0.750	0.850	0.030	0.033
E1	1.150	1.250	0.045	0.049
e	0.400 BSC.		0.016 BSC.	
e1	0.800 BSC.		0.032 BSC.	
L	0.150	0.250	0.006	0.010
Θ	7°	11°	7°	11°